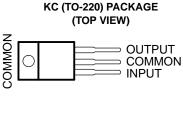
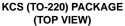
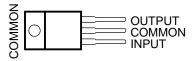


FEATURES

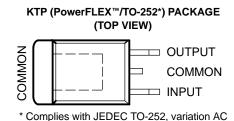
- 3-Terminal Regulators
- Output Current up to 500 mA
- No External Components
- Internal Thermal-Overload Protection

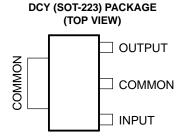






- High Power-Dissipation Capability
- Internal Short-Circuit Current Limiting
- Output Transistor Safe-Area Compensation





DESCRIPTION/ORDERING INFORMATION

This series of fixed-voltage integrated-circuit voltage regulators is designed for a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single-point regulation. Each of these regulators can deliver up to 500 mA of output current. The internal current-limiting and thermal-shutdown features of these regulators essentially make them immune to overload. In addition to use as fixed-voltage regulators, these devices can be used with external components to obtain adjustable output voltages and currents and also as the power-pass element in precision regulators.

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Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerFLEX, PowerPAD are trademarks of Texas Instruments.

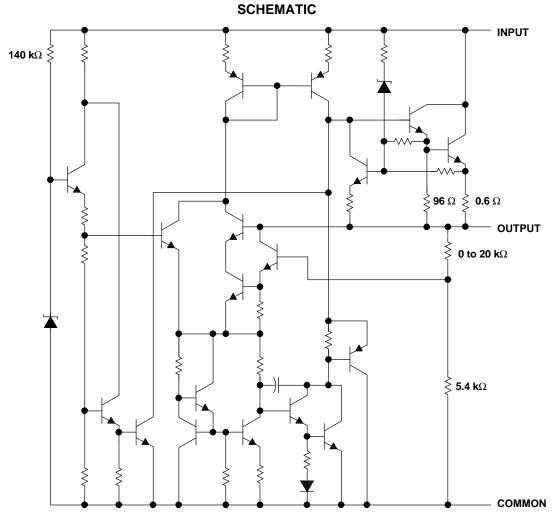


ORDERING INFORMATION

T _A	V _O (NOM) (V)	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
		PowerFLEX TM /TO-252 ⁽²⁾ – KTP	Reel of 3000	μΑ78M33CKTPR	UA78M33C
	3.3	SOT-223 – DCY	Tube of 80	μΑ78M33CDCY	C3
	3.3	301-223 - DC1	Reel of 2500	μΑ78M33CDCYR	CS
		TO-220 – KC	Tube of 50	μΑ78М33СКС	UA78M33C
		PowerFLEX/TO-252 ⁽²⁾ – KTP	Reel of 3000	μΑ78M05CKTPR	UA78M05C
		SOT-223 – DCY	Tube of 80	μΑ78M05CDCY	C5
	5	301-223 - DC1	Reel of 2500	μΑ78M05CDCYR	CS
		TO-220 – KC	Tube of 50	μΑ78M05CKC	UA78M05C
0°C to 125°C		TO-220, short shoulder – KCS	Tube of 20	μΑ78M05CKCS	UA/6IVIUSC
0 C to 125 C	6	PowerFLEX/TO-252 ⁽²⁾ – KTP	Reel of 3000	μΑ78M06CKTPR	UA78M06C
		PowerFLEX/TO-252 ⁽²⁾ – KTP	Reel of 3000	μΑ78M08CKTPR	UA78M08C
	8	SOT-223 – DCY	Tube of 80	μΑ78M08CDCY	C8
	0	301-223 - DC1	Reel of 2500	μΑ78M08CDCYR	Co
		TO-220 – KC	Tube of 50	μΑ78M08CKC	UA78M08C
	9	PowerFLEX/TO-252 ⁽²⁾ – KTP	Reel of 3000	μΑ78M09CKTPR	UA78M09C
	10	PowerFLEX/TO-252 ⁽²⁾ – KTP	Reel of 3000	μΑ78M10CKTPR	UA78M10C
	12	PowerFLEX/TO-252 ⁽²⁾ – KTP	Reel of 3000	μΑ78M12CKTPR	UA78M12C
	12	TO-220 – KC	Tube of 50	μΑ78M12CKC	UA78M12C
·		PowerFLEX/TO-252 ⁽²⁾ – KTP	Reel of 3000	μΑ78M05IKTPR	UA78M05I
		SOT-223 – DCY	Tube of 80	μΑ78M05IDCY	J5
–40°C to 125°C	5	301-223 - DO1	Reel of 2500	μΑ78M05IDCYR	33
		TO-220 – KC	Tube of 50	μΑ78M05IKC	UA78M05I
		TO-220, short shoulder – KCS	Tube of 20	μΑ78M05IKCS	OA7 OWOO

 ⁽¹⁾ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
 (2) Complies with JEDEC TO-252, variation AC





Resistor values shown are nominal.

μΑ78M00 SERIES POSITIVE-VOLTAGE REGULATORS





Absolute Maximum Ratings(1)

over virtual junction temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{I}	Input voltage		35	V
T_J	Operating virtual junction temperature		150	°C
T _{sta}	Storage temperature range	-65	150	°C

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Package Thermal Data⁽¹⁾

PACKAGE	BOARD	θ _{JP} ⁽²⁾	θјС	θ_{JA}
PowerFLEX/TO-252 - KTP	High K, JESD 51-5	1.4°C/W	19°C/W	28°C/W
SOT-223 - DCY	High K, JESD 51-7		30.6°C/W	53°C/W
TO-220 - KC/KCS	High K, JESD 51-5	3°C/W	17°C/W	19°C/W

⁽¹⁾ Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.

Recommended Operating Conditions

			MIN	MAX	UNIT
		μΑ78Μ33	5.3	25	
		μΑ78Μ05	7	25	
		μΑ78Μ06	8	25	
\/	Input valtage	μΑ78Μ08	10.5	25	V
VI	Input voltage	μΑ78Μ09	11.5	26	V
		μΑ78Μ10	12.5	28	
		μA78M12	14.5	30	
		μA78M15	17.5	30	
Io	Output current			500	mA
т	Operating virtual junction temporature	μΑ78MxxC	0	125	°C
TJ	Operating virtual junction temperature	μΑ78MxxI	-40	125	

⁽²⁾ For packages with exposed thermal pads, such as QFN, PowerPAD™, or PowerFLEX, θ_{JP} is defined as the thermal resistance between the die junction and the bottom of the exposed pad.



at specified virtual junction temperature, $V_I = 8 \text{ V}$, $I_O = 350 \text{ mA}$, $T_J = 25^{\circ}\text{C}$ (unless otherwise noted)

DADAMETED	TEST CONDITIONS(1)			μ Α78Μ33C			
PARAMETER	IESI	TEST CONDITIONS.			MAX	UNIT	
Output valtage (2)	$I_0 = 5 \text{ mA to } 350 \text{ mA},$		3.2	3.3	3.4	V	
Output voltage ⁽²⁾	$V_1 = 8 \text{ V to } 20 \text{ V}$	$T_J = 0$ °C to 125°C	3.1	3.3	3.5		
Input valtage regulation	1 200 m A	V _I = 5.3 V to 25 V		9	100	\/	
Input voltage regulation	I _O = 200 mA	V _I = 8 V to 25 V		3	50	mV	
Ripple rejection	$V_1 = 8 \text{ V to } 18 \text{ V},$	$I_{O} = 100 \text{ mA}, T_{J} = 0^{\circ}\text{C to } 125^{\circ}\text{C}$	62			-10	
	f = 120 Hz	I _O = 300 mA	62	80		dB	
Output voltage regulation	V _I = 8 V,	I _O = 5 mA to 500 mA		20	100	mV	
Temperature coefficient of output voltage	I _O = 5 mA,	T _J = 0°C to 125°C		-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz			40	200	μV	
Dropout voltage				2		V	
Bias current				4.5	6	mA	
Dies sument shares	$I_{O} = 200 \text{ mA}, V_{I} = 8 \text{ V to } 25 \text{ V}$	T , $T_J = 0$ °C to 125°C			8.0	A	
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	mA to 350 mA, $T_J = 0$ °C to 125°C			0.5	mA	
Short-circuit output current	V _I = 35 V			300		mA	
Peak output current				700		mA	

All characteristics are measured with a 0.33-µF capacitor across the input and a 0.1-µF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately. This specification applies only for dc power dissipation permitted by absolute maximum ratings

Electrical Characteristics

at specified virtual junction temperature, $V_I = 10 \text{ V}$, $I_O = 350 \text{ mA}$, $T_J = 25^{\circ}\text{C}$ (unless otherwise noted)

DADAMETED	TEST CONDITIONS ⁽¹⁾		μ Α78M05C			UNIT	
PARAMETER	IES	TEST CONDITIONS.			MAX	UNII	
Output voltage	I _O = 5 mA to 350 mA,		4.8	5	5.2	V	
Output voltage	$V_I = 7 \text{ V to } 20 \text{ V}$	$T_J = 0$ °C to 125°C	4.75		5.25	V	
Input voltage regulation	I _O = 200 mA	V _I = 7 V to 25 V		3	100	mV	
input voitage regulation	1 ₀ = 200 IIIA	V _I = 8 V to 25 V		1	50	IIIV	
Pinnla raigation	V _I = 8 V to 18 V,	$I_{O} = 100 \text{ mA}, T_{J} = 0^{\circ}\text{C to } 125^{\circ}\text{C}$	62			dB	
Ripple rejection	f = 120 Hz	I _O = 300 mA	62	80		uВ	
Output voltage regulation	I _O = 5 mA to 500 mA	I _O = 5 mA to 500 mA		20	100	mV	
	$I_O = 5 \text{ mA to } 200 \text{ mA}$			10	50	IIIV	
Temperature coefficient of output voltage	I _O = 5 mA,	$T_J = 0$ °C to 125°C		-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz			40	200	μV	
Dropout voltage				2		V	
Bias current				4.5	6	mA	
Diag current change	$I_O = 200 \text{ mA}, V_I = 8 \text{ V to } 25$	V, $T_J = 0^{\circ}C$ to 125°C			0.8	A	
Bias current change	$I_0 = 5 \text{ mA to } 350 \text{ mA},$	$T_J = 0$ °C to 125°C			0.5	mA 5	
Short-circuit output current	V _I = 35 V			300		mA	
Peak output current				0.7		Α	

⁽¹⁾ All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.



at specified virtual junction temperature, $V_I = 10 \text{ V}$, $I_O = 350 \text{ mA}$, $T_J = 25^{\circ}\text{C}$ (unless otherwise noted)

DADAMETED	TEST CONDITIONS ⁽¹⁾		μ	μ Α78M05I			
PARAMETER	'	EST CONDITIONS(*)	MIN	TYP	MAX	UNIT	
Output valtage	I _O = 5 mA to 350 mA, V _I = 7 V to 20 V		4.8	5	5.2	V	
Output voltage		$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$	4.75		5.25	V	
Input valtage regulation	1 200 mA	V _I = 7 V to 25 V		3	100	mV	
Input voltage regulation	I _O = 200 mA	V _I = 8 V to 25 V		1	50	IIIV	
Ripple rejection	$V_1 = 8 \text{ V to } 18 \text{ V},$	$I_{O} = 100 \text{ mA}, T_{J} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$	62			J.	
	f = 120 Hz	I _O = 300 mA	62	80		dB	
Outrot valtana na mandatian	I _O = 5 mA to 500 mA			20	100	\/	
Output voltage regulation	I _O = 5 mA to 200 mA			10	50	mV	
Temperature coefficient of output voltage	I _O = 5 mA,	$T_{J} = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$		-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz			40	200	μV	
Dropout voltage				2		V	
Bias current				4.5	6	mA	
Dies sument shares	$I_0 = 200 \text{ mA}, V_1 = 8 \text{ V to } 200 \text{ mA}$	25 V, T _J = -40°C to 125°C			0.8	mA	
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			0.5		
Short-circuit output current	V _I = 35 V			300		mA	
Peak output current				0.7		Α	

⁽¹⁾ All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.

Electrical Characteristics

at specified virtual junction temperature, V_I = 11 V, I_O = 350 mA, T_J = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS ⁽¹⁾			μ Α	μ Α78Μ06C		
PARAMETER	TEST CONDITIONS.				TYP	MAX	UNIT
Output voltage	L = 5 mΛ to 250 mΛ	\/ - 9 \/ +0 21 \/		5.75	6	6.25 V	V
Output voltage	$I_0 = 5 \text{ mA to } 350 \text{ mA},$	$V_1 = 8 \text{ V to } 21 \text{ V}$	$T_J = 0$ °C to 125°C	5.7		6.3	V
Input voltage regulation	1 200 m A	$V_{I} = 8 \text{ V to } 25 \text{ V}$			5	100	mV
input voltage regulation	I _O = 200 mA	$V_{I} = 9 \text{ V to } 25 \text{ V}$			1.5	50	IIIV
Ripple rejection	V _I = 8 V to 18 V,	f = 120 Hz	$I_{O} = 100 \text{ mA},$ $T_{J} = 0^{\circ}\text{C to } 125^{\circ}\text{C}$	59			dB
			I _O = 300 mA	59	80		
Output voltage regulation	$I_O = 5$ mA to 500 mA				20	120	mV
	$I_O = 5$ mA to 200 mA				10	60	IIIV
Temperature coefficient of output voltage	I _O = 5 mA,	$T_J = 0$ °C to 125°C			-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz				45		μV
Dropout voltage					2		V
Bias current					4.5	6	mA
Dies surrent change	$V_{I} = 9 V \text{ to } 25 V,$	$I_0 = 200 \text{ mA},$	$T_J = 0^{\circ}C$ to $125^{\circ}C$			0.8	A
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = 0$ °C to 125°C				0.5	mA
Short-circuit output current	V _I = 35 V				270		mA
Peak output current					0.7		Α

⁽¹⁾ All characteristics are measured with a $0.33-\mu F$ capacitor across the input and a $0.1-\mu F$ capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.



at specified virtual junction temperature, $V_I = 14 \text{ V}$, $I_O = 350 \text{ mA}$, $T_J = 25^{\circ}\text{C}$ (unless otherwise noted)

DADAMETED	TEST CONDITIONS ⁽¹⁾			μ Δ	μ Α78Μ08C		
PARAMETER		MIN	TYP	MAX	UNIT		
Output voltage	$V_1 = 10.5 \text{ V to } 23 \text{ V},$	I − Ε mΛ to 2Ε0 mΛ		7.7	8	8.3	V
Output voltage	V ₁ = 10.5 V to 25 V,	$I_O = 5 \text{ mA to } 350 \text{ mA}$	$T_J = 0$ °C to 125°C	7.6		8.4	٧
Input voltage regulation	I _O = 200 mA	$V_I = 10.5 \text{ V to } 25 \text{ V}$			6	100	mV
	1 ₀ = 200 IIIA	$V_{I} = 11 \text{ V to } 25 \text{ V}$			2	50	IIIV
Dinale rejection	$V_I = 11 \text{ V to } 21.5 \text{ V},$	$I_{O} = 100 \text{ mA},$	$T_J = 0^{\circ}C$ to $125^{\circ}C$	56			dB
Ripple rejection	f = 120 Hz	I _O = 300 mA		56	80		uБ
Output voltage regulation	I _O = 5 mA to 500 mA				25	160	mV
	I _O = 5 mA to 200 mA				10	80	IIIV
Temperature coefficient of output voltage	I _O = 5 mA,	$T_J = 0^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz				52		μV
Dropout voltage					2		V
Bias current					4.6	6	mA
Diag gurrant abanga	V _I = 10.5 V to 25 V,	I _O = 200 mA,	$T_J = 0$ °C to 125°C			0.8	A
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = 0^{\circ}C$ to $125^{\circ}C$				0.5	mA
Short-circuit output current	V _I = 35 V				250		mA
Peak output current					0.7		Α

⁽¹⁾ All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.

Electrical Characteristics

at specified virtual junction temperature, V_I = 16 V, I_O = 350 mA, T_J = 25°C (unless otherwise noted)

DADAMETER	TEST CONDITIONS ⁽¹⁾			μ Δ	μ Α78Μ09C			
PARAMETER	TEST CONDITIONS(*)				TYP	MAX	UNIT	
Output voltage	$V_1 = 11.5 \text{ V to } 24 \text{ V},$	I − Ε mΛ to 2Ε0 mΛ		8.6	9	9.4	V	
Output voltage	V ₁ = 11.5 V tO 24 V,	$I_O = 5 \text{ mA to } 350 \text{ mA}$	$T_J = 0$ °C to 125°C	8.5		9.5	V	
Input voltage regulation	L = 200 mA	$V_I = 11.5 \text{ V to } 26 \text{ V}$			6	100	mV	
	I _O = 200 mA	V _I = 12 V to 26 V			2	50	mv	
Dinale rejection	V _I = 13 V to 23 V,	I _O = 100 mA,	$T_J = 0$ °C to 125°C	56			dB	
Ripple rejection	f = 120 Hz	I _O = 300 mA		56	80		uБ	
Output valta na na mulatia n	I _O = 5 mA to 500 mA				25	180	mV	
Output voltage regulation	$I_O = 5$ mA to 200 mA				10	90	IIIV	
Temperature coefficient of output voltage	I _O = 5 mA,	$T_J = 0^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz				58		μV	
Dropout voltage					2		V	
Bias current					4.6	6	mA	
Dian august shaasa	V _I = 11.5 V to 26 V,	I _O = 200 mA,	$T_J = 0$ °C to 125°C			0.8	Λ	
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = 0^{\circ}C$ to $125^{\circ}C$				0.5	mA	
Short-circuit output current	V _I = 35 V				250		mA	
Peak output current					0.7		Α	

⁽¹⁾ All characteristics are measured with a $0.33-\mu F$ capacitor across the input and a $0.1-\mu F$ capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.



at specified virtual junction temperature, $V_1 = 17 \text{ V}$, $I_0 = 350 \text{ mA}$, $T_J = 25^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS ⁽¹⁾			μΑ	μ Α78Μ10C			
PARAMETER		TEST CONDITIONS(1)	MIN			MAX	UNIT	
Output voltage	V = 12 5 V to 25 V	I − Ε mΛ to 2Ε0 mΛ		9.6	10	10.4	V	
Output voltage	$V_I = 12.5 \text{ V to } 25 \text{ V},$	$I_O = 5 \text{ mA to } 350 \text{ mA}$	$T_J = 0$ °C to 125°C	9.5		10.5	V	
Input voltage regulation	1 200 m A	$V_I = 12.5 \text{ V to } 28 \text{ V}$			7	100	mV	
	I _O = 200 mA	$V_{I} = 14 \text{ V to } 28 \text{ V}$			2	50	IIIV	
Dinale rejection	$V_{I} = 15 \text{ V to } 25 \text{ V},$	$I_{O} = 100 \text{ mA},$	$T_J = 0^{\circ}C$ to $125^{\circ}C$	59			dB	
Ripple rejection	f = 120 Hz	I _O = 300 mA		55	80		uБ	
Outside all sections are made the se	I _O = 5 mA to 500 mA				25	200	mV	
Output voltage regulation	I _O = 5 mA to 200 mA				10	100		
Temperature coefficient of output voltage	I _O = 5 mA,	$T_J = 0^{\circ}C$ to 125°C			-1		mV/°C	
Output noise voltage	f = 10 Hz to 100 kHz				64		μV	
Dropout voltage					2		V	
Bias current					4.7	6	mA	
Pice current change	$V_I = 12.5 \text{ V to } 28 \text{ V},$	$I_0 = 200 \text{ mA},$	$T_J = 0^{\circ}C$ to $125^{\circ}C$			8.0	mA	
Bias current change	$I_O = 5$ mA to 350 mA,	$T_J = 0$ °C to 125°C				0.5	ША	
Short-circuit output current	V _I = 35 V				245		mA	
Peak output current					0.7		Α	

⁽¹⁾ All characteristics are measured with a 0.33-μF capacitor across the input and a 0.1-μF capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.

Electrical Characteristics

at specified virtual junction temperature, V_I = 19 V, I_O = 350 mA, T_J = 25°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS ⁽¹⁾			μΑ	μ Α78M12C		
PARAMETER	TEST CONDITIONS(1)				TYP	MAX	UNIT
Output voltage	V _I = 14.5 V to 27 V,	I − Ε mΛ to 2Ε0 mΛ		11.5	12	12.5	V
Output voltage	$V_1 = 14.5 \text{ V to } 27 \text{ V},$	$I_O = 5 \text{ mA to } 350 \text{ mA}$	$T_J = 0$ °C to 125°C	11.4		12.6	V
Input voltage regulation	1 200 m A	$V_1 = 14.5 \text{ V to } 30 \text{ V}$			8	100	mV
	I _O = 200 mA	V _I = 16 V to 30 V			2	50	IIIV
Dinale rejection	V _I = 15 V to 25 V,	I _O = 100 mA,	$T_J = 0$ °C to 125°C	55			dB
Ripple rejection	f = 120 Hz	I _O = 300 mA		55	80		uБ
Output voltage regulation	I _O = 5 mA to 500 mA				25	240	mV
	I _O = 5 mA to 200 mA				10	120	IIIV
Temperature coefficient of output voltage	I _O = 5 mA,	$T_J = 0^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$			-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz				75		μV
Dropout voltage					2		V
Bias current					4.8	6	mA
Diag summent shapes	$V_I = 14.5 \text{ V to } 30 \text{ V},$	I _O = 200 mA,	$T_J = 0$ °C to 125°C			8.0	A
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA},$	$T_J = 0^{\circ}C$ to $125^{\circ}C$				0.5	mA
Short-circuit output current	V _I = 35 V				240		mA
Peak output current					0.7		Α

⁽¹⁾ All characteristics are measured with a $0.33-\mu F$ capacitor across the input and a $0.1-\mu F$ capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.



The μ A78M15 is obsolete and no longer supplied.

Electrical Characteristics

at specified virtual junction temperature, $V_1 = 23 \text{ V}$, $I_0 = 350 \text{ mA}$, $T_J = 25^{\circ}\text{C}$ (unless otherwise noted)

DADAMETED		μ Δ	LINUT				
PARAMETER		MIN	TYP	MAX	UNIT		
Output voltage	V _I = 17.5 V to 30 V,	L = 5 mΛ to 250 mΛ		14.4	15	15.6	V
	$V_1 = 17.5 \text{ V to 30 V},$	$I_O = 5 \text{ mA to } 350 \text{ mA}$	$T_J = 0$ °C to 125°C	14.25		15.75	V
Input voltage regulation	1 200 mA	$V_1 = 17.5 \text{ V to } 30 \text{ V}$		10	100	mV	
	I _O = 200 mA	V _I = 20 V to 30 V		3	50	IIIV	
Ripple rejection	V _I = 18.5 V to 28.5 V,	$I_{O} = 100 \text{ mA},$ $T_{J} = 0^{\circ}\text{C to } 125^{\circ}\text{C}$		54			dB
	f = 120 Hz	I _O = 300 mA	54	70		uБ	
Output voltage regulation	I _O = 5 mA to 500 mA		25	300	mV		
	$I_O = 5$ mA to 200 mA		10	150	IIIV		
Temperature coefficient of output voltage	I _O = 5 mA,	$T_J = 0$ °C to 125°C			-1		mV/°C
Output noise voltage	f = 10 Hz to 100 kHz				90		μV
Dropout voltage					2		V
Bias current					4.8	6	mA
D'an annual al annua	V _I = 17.5 V to 30 V,	$I_{O} = 200 \text{ mA}, \qquad T_{J} = 0^{\circ}\text{C to}$				0.8	A
Bias current change	$I_{O} = 5 \text{ mA to } 350 \text{ mA}, T_{J} = 0^{\circ}\text{C to } 125^{\circ}\text{C}$					0.5	mA
Short-circuit output current	V _I = 35 V				240		mA
Peak output current					0.7		Α

⁽¹⁾ All characteristics are measured with a $0.33-\mu F$ capacitor across the input and a $0.1-\mu F$ capacitor across the output. Pulse-testing techniques maintain T_J as close to T_A as possible. Thermal effects must be taken into account separately.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UA78M05CDCY	ACTIVE	SOT-223	DCY	4	80	TBD	CU SN	Level-2-235C-1 YEAR
UA78M05CDCYG3	ACTIVE	SOT-223	DCY	4	80	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1YEAR
UA78M05CDCYR	ACTIVE	SOT-223	DCY	4	2500	TBD	CU SN	Level-2-235C-1 YEAR
UA78M05CDCYRG3	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1YEAR
UA78M05CKC	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M05CKCS	ACTIVE	TO-220	KCS	3	50	TBD	CU SN	N / A for Pkg Type
UA78M05CKTPR	NRND	PFM	KTP	2	3000	TBD	CU SNPB	Level-1-220C-UNLIM
UA78M05CKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M05CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
UA78M05IDCY	ACTIVE	SOT-223	DCY	4	80	TBD	CU SN	Level-2-235C-1 YEAR
UA78M05IDCYG3	ACTIVE	SOT-223	DCY	4	80	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1YEAR
UA78M05IDCYR	ACTIVE	SOT-223	DCY	4	2500	TBD	CU SN	Level-2-235C-1 YEAR
UA78M05IDCYRG3	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1YEAR
UA78M05IKC	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M05IKCE3	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M05IKCS	ACTIVE	TO-220	KCS	3	50	TBD	CU SN	N / A for Pkg Type
UA78M05IKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M05IKTPR	NRND	PFM	KTP	2	3000	TBD	CU SNPB	Level-1-220C-UNLIM
UA78M05IKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M05IKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
UA78M06CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA78M06CKTPR	NRND	PFM	KTP	2	3000	TBD	CU SNPB	Level-1-220C-UNLIM
UA78M06CKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M06CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
UA78M08CDCY	ACTIVE	SOT-223	DCY	4	80	TBD	CU SN	Level-2-235C-1 YEAR
UA78M08CDCYG3	ACTIVE	SOT-223	DCY	4	80	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1YEAR
UA78M08CDCYR	ACTIVE	SOT-223	DCY	4	2500	TBD	CU SN	Level-2-235C-1 YEAR
UA78M08CDCYRG3	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1YEAR
UA78M08CKC	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
		TO-220	KC	3	50	Pb-Free	CU SN	N / A for Pkg Type





om 27-Oct-2006

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						(RoHS)		
UA78M08CKCS	ACTIVE	TO-220	KCS	3	50	TBD	CU SN	N / A for Pkg Type
UA78M08CKTPR	NRND	PFM	KTP	2	3000	TBD	CU SNPB	Level-1-220C-UNLIM
UA78M08CKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M08CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR
UA78M09CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA78M09CKTP	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI
UA78M09CKTPR	NRND	PFM	KTP	2	3000	TBD	CU SNPB	Level-1-220C-UNLIM
UA78M09CKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M09CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HF
UA78M10CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA78M10CKTPR	NRND	PFM	KTP	2	3000	TBD	CU SNPB	Level-1-220C-UNLIM
UA78M10CKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M10CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HF
UA78M12CKC	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M12CKCS	ACTIVE	TO-220	KCS	3	50	TBD	CU SN	N / A for Pkg Type
UA78M12CKTPR	NRND	PFM	KTP	2	3000	TBD	CU SNPB	Level-1-220C-UNLIM
UA78M12CKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M12CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HF
UA78M15CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA78M15CKTPR	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI
UA78M20CKC	OBSOLETE	TO-220	KC	3		TBD	Call TI	Call TI
UA78M20CKTPR	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI
UA78M20Y	OBSOLETE	XCEPT	Υ	0		TBD	Call TI	Call TI
UA78M24CKTPR	OBSOLETE	PFM	KTP	2		TBD	Call TI	Call TI
UA78M33CDCY	ACTIVE	SOT-223	DCY	4	80	TBD	CU SN	Level-2-235C-1 YEAI
UA78M33CDCYG3	ACTIVE	SOT-223	DCY	4	80	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1YEAF
UA78M33CDCYR	ACTIVE	SOT-223	DCY	4	2500	TBD	CU SN	Level-2-235C-1 YEAI
UA78M33CDCYRG3	ACTIVE	SOT-223	DCY	4	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1YEAF
UA78M33CKC	NRND	TO-220	КС	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M33CKCE3	NRND	TO-220	KC	3	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type
UA78M33CKCS	ACTIVE	TO-220	KCS	3	50	TBD	CU SN	N / A for Pkg Type
UA78M33CKCSE3	ACTIVE	TO-220	KCS	3	50	Pb-Free (RoHS)		N / A for Pkg Type
UA78M33CKTPR	NRND	PFM	KTP	2	3000	TBD	CU SNPB	Level-1-220C-UNLIM



PACKAGE OPTION ADDENDUM

27-Oct-2006

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins P	ackage Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
UA78M33CKTPRG3	NRND	PFM	KTP	2	3000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM
UA78M33CKVURG3	ACTIVE	PFM	KVU	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

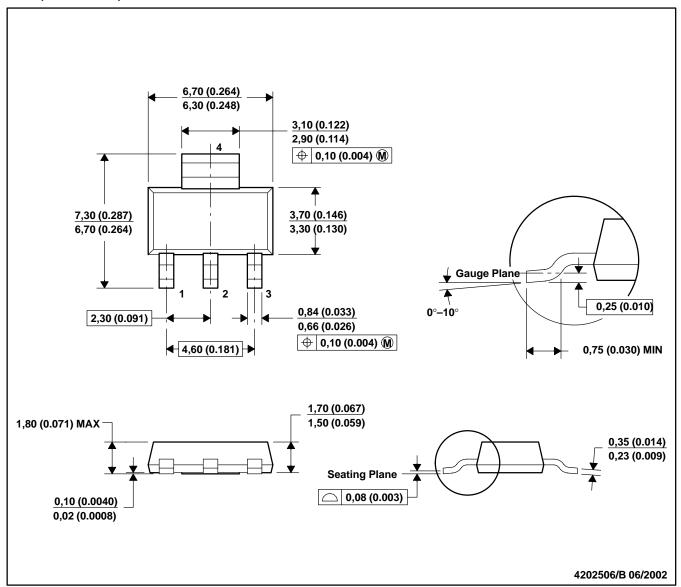
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DCY (R-PDSO-G4)

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters (inches).

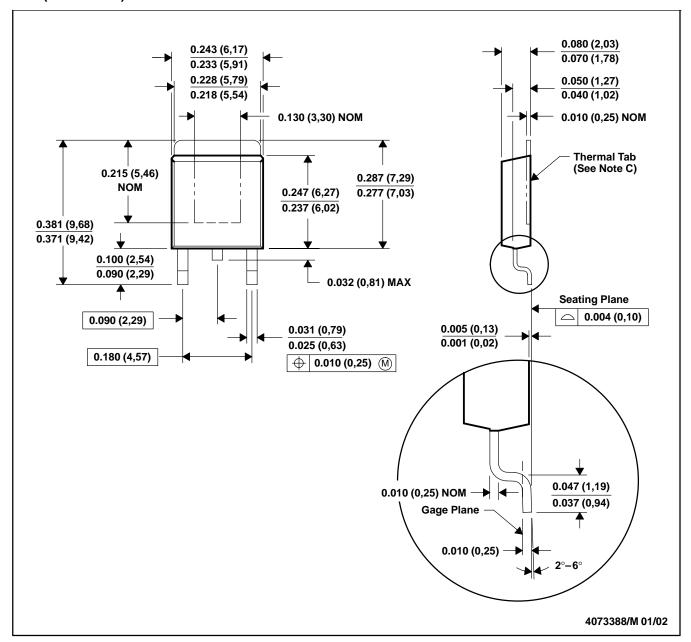
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC TO-261 Variation AA.

KTP (R-PSFM-G2)

PowerFLEX™ PLASTIC FLANGE-MOUNT PACKAGE



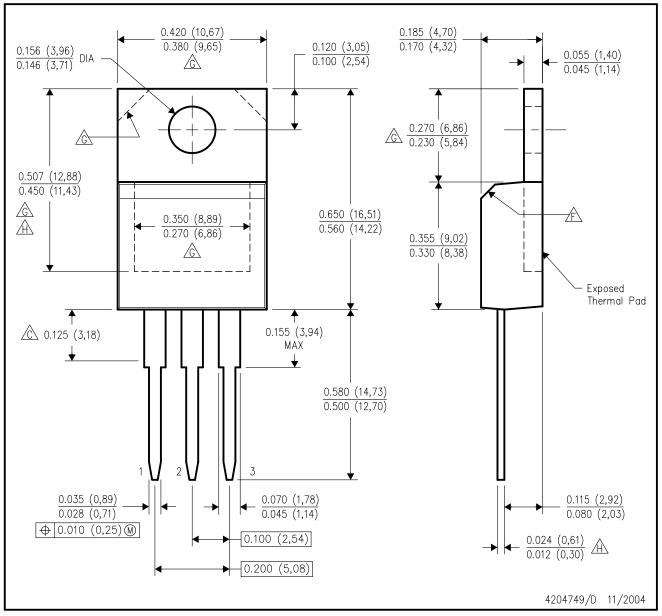
- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. The center lead is in electrical contact with the thermal tab.
 - D. Dimensions do not include mold protrusions, not to exceed 0.006 (0,15).
 - E. Falls within JEDEC TO-252 variation AC.

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KCS (R-PSFM-T3)

PLASTIC FLANGE-MOUNT PACKAGE



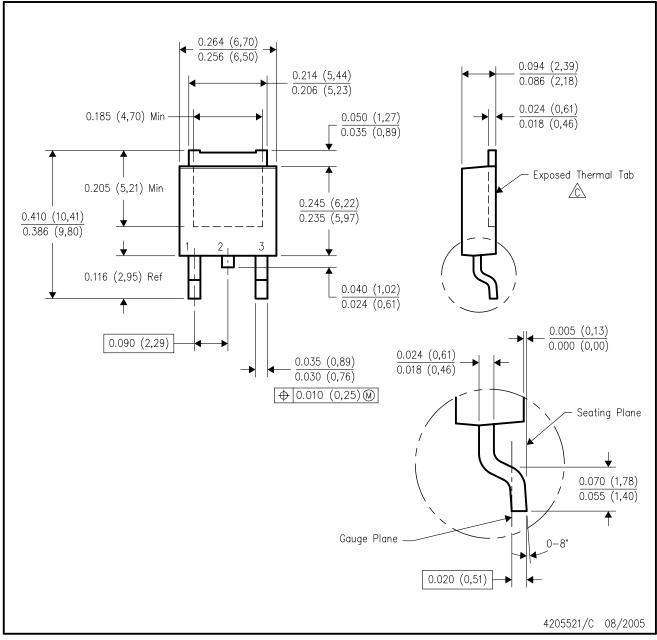
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC T0—220 variation AB, except minimum lead thickness and minimum exposed pad length.



KVU (R-PSFM-G3)

PLASTIC FLANGE-MOUNT PACKAGE



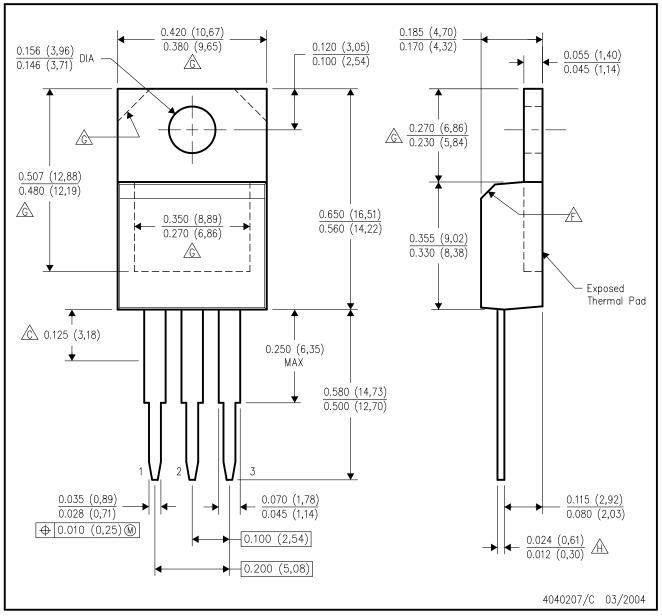
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- The center lead is in electrical contact with the exposed thermal tab.
- D. Body Dimensions do not include mold flash or protrusions. Mold flash and protrusion shall not exceed 0.006 (0,15) per side.
- E. Falls within JEDEC TO-252 variation AA.



KC (R-PSFM-T3)

PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A. All linear

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
- D. All lead dimensions apply before solder dip.
- E. The center lead is in electrical contact with the mounting tab.
- The chamfer is optional.
- Thermal pad contour optional within these dimensions.
- Falls within JEDEC TO-220 variation AB, except minimum lead thickness.



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